Collected charge, gain and jitter measurements of unirradiated LGADs from Teledyne e2v

39th RD50 Workshop, 18th November 2021

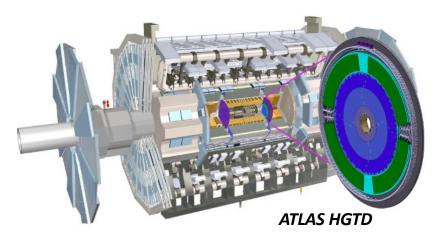
P. Allport, D. Bortoletto, <u>M. Gazi</u>, L. Gonella, D. Hynds, D. Jordan, I. Kopsalis, S. McMahon, J. Mulvey, R. Plackett, K. Stefanov, E. G. Villani



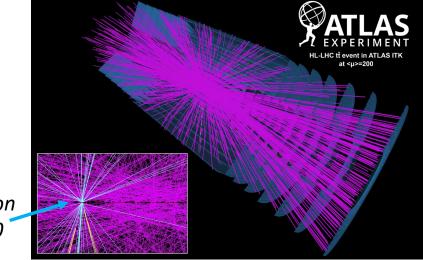
Outline

- Introduction: Ultra Fast Silicon Detectors
- Project overview: LGADs manufactured by Teledyne e2v
- Amplifier SPICE simulation
- Collected charge measurements
- Gain measurements
- Jitter measurements
- Future plans
- Summary

The need for Ultra Fast Silicon Detectors



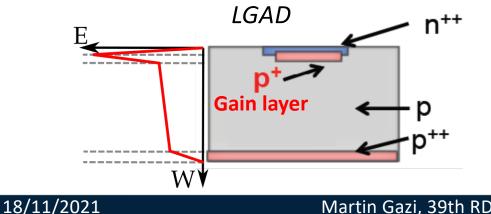
1 pp interaction amongst 200

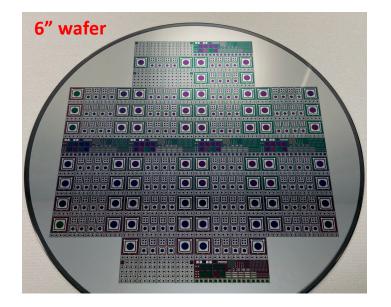


- Pile-up is one of the major challenges for tracking at the HL-LHC
- Timing information used to disentangle overlapping events
- ATLAS High-Granularity Timing Detector placed outside the ITk

Teledyne e2v LGAD project

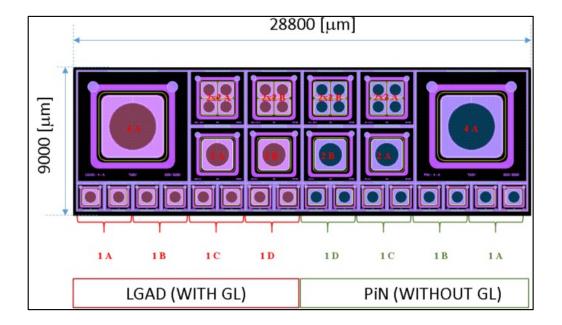
- LGAD: Low Gain Avalanche Detector
- Targeting track timing resolution of approx. 30-50 ps over detector lifetime
 - Time resolution benefits from high slew rate -> increased by introducing internal gain
 - Impact ionization in gain layer -> boron implantation (p⁺)
- Pre-manufacture simulation done in TCAD
- University of Oxford, University of Birmingham, Open University, Rutherford Appleton Laboratory





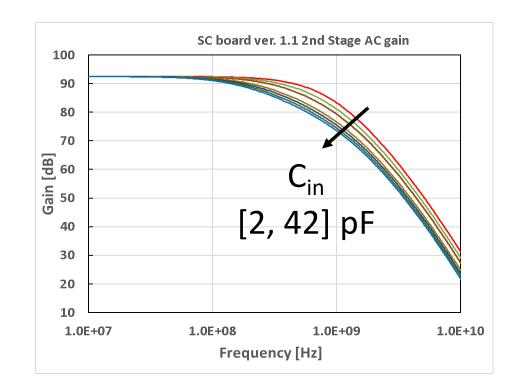
Teledyne e2v LGAD project

- Epitaxial layer: 50 um thick, high resistivity
- 8 different combinations of manufacturing parameters (only 3 shown below)
- Each field contains LGADs and PiN diodes of the same layout (4 mm, 2 mm, 1 mm)



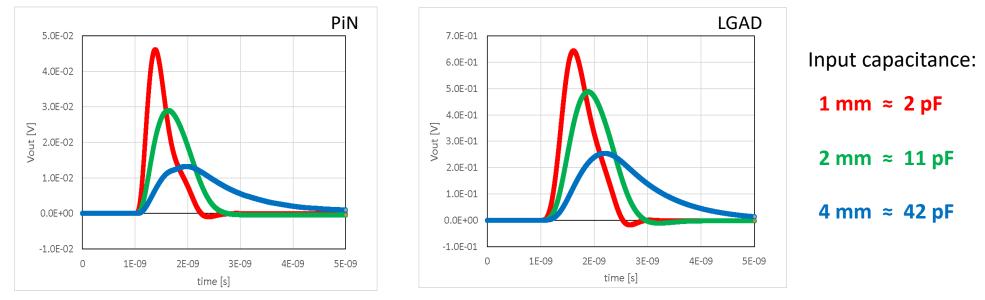
Charge gain measurement - amplification

- First stage amplifier: Santa Cruz Readout v1.1
- Second stage amplifier: FEMTO HSA-X-2-40, 40 dB – 2GHz
- Impedance matched to 50 Ohm
- The combined effect of the chain of amplifiers simulated in SPICE
 - Estimate the gain of the chain
 - Gain: 92.5 dB or 42,170 for 1mm devices with 2 pF capacitance
- Temperature is set to 25°C



SPICE – Transient current simulation of MIP signal

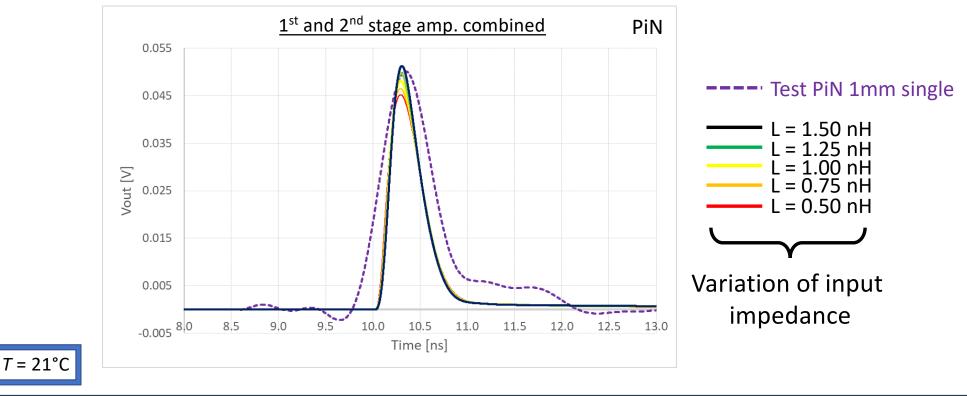
1st and 2nd stage amp. combined



PiN signal: assuming saturated carrier velocity, peak current 1.5 uA with e⁻ collection time 300 ps, h⁺ collection time 1 ns LGAD signal: peak current 15 uA (10x of PIN signal)

SPICE – Transient current simulation

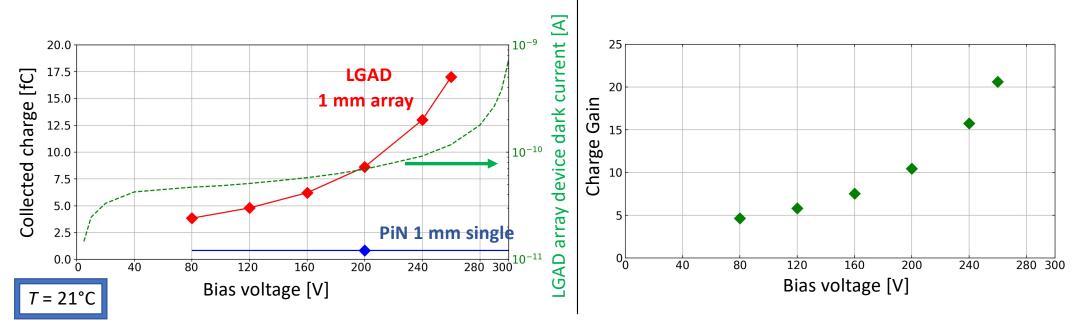
- PiN signal from TCAD simulation, input capacitance C_{in} = 2 pF
- Calibration of the laser to inject MIP-like amount of charge



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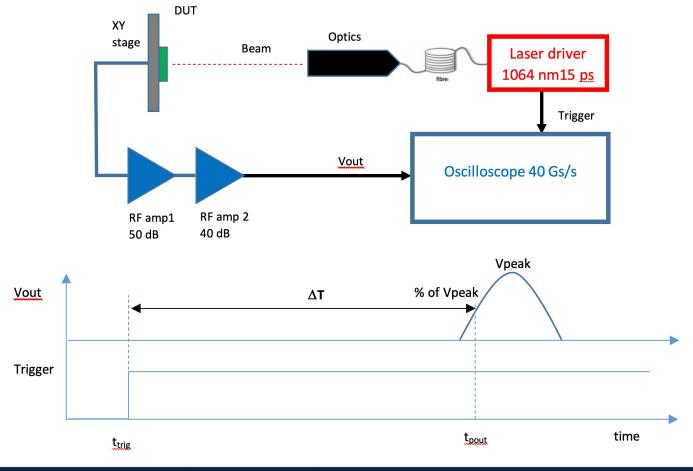
Charge collected and gain measurements – 1mm

- Conversion from the amplifier output to collected charge by estimating the gain of the chain of amplifiers from a SPICE simulation (92.5 dB or 42,170 for C_{in} of 2 pF – assumed constant up to 1.5 GHz)
- The charge gain the ratio of the charge collected by LGAD and PiN



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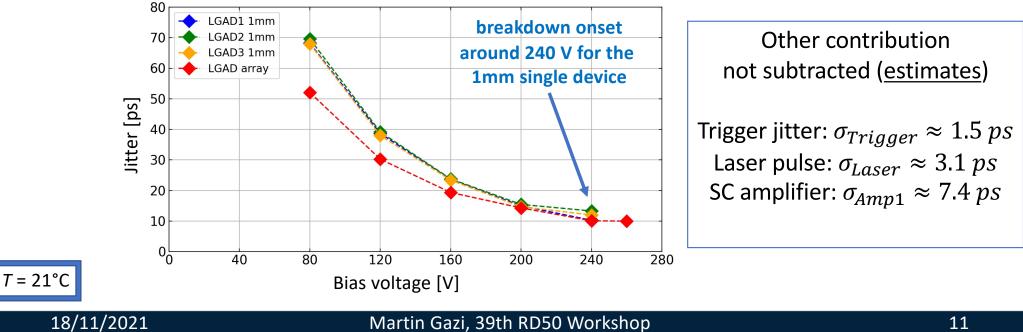
Jitter measurements - setup



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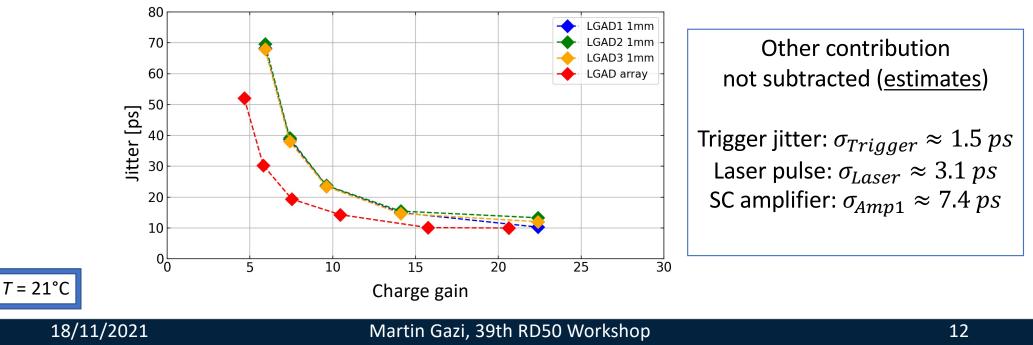
Jitter measurements – 1mm LGAD (single and array)

- Jitter the spread (standard deviation) of time delay between 50 % of trigger signal amplitude and 50 % of LGAD signal amplitude
- Low pass filter applied at 1 GHz no substantial change to the signal
- Unirradiated device; no subtraction of other contributions



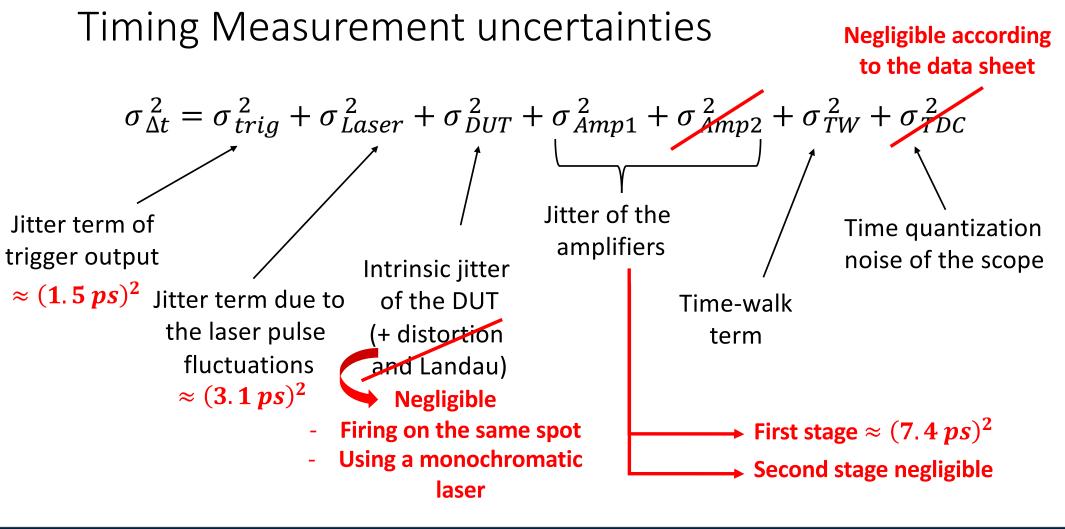
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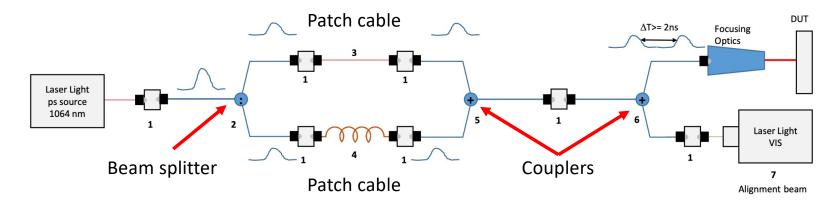
Timing Measurement uncertainties

$$\sigma_{\Delta t}^{2} = \sigma_{trig}^{2} + \sigma_{Laser}^{2} + \sigma_{DUT}^{2} + \sigma_{Amp1}^{2} + \sigma_{Amp2}^{2} + \sigma_{TW}^{2} + \sigma_{TDC}^{2}$$
Jitter term of
trigger output
Intrinsic jitter
Jitter term due to
of the DUT
the laser pulse
(+ distortion
and Landau)
Time-walk
term



Future tests

• Jitter measurements – elimination of the laser trigger component



- Test with the other produced wafers variation of implant dose and energy
- Irradiation of the devices

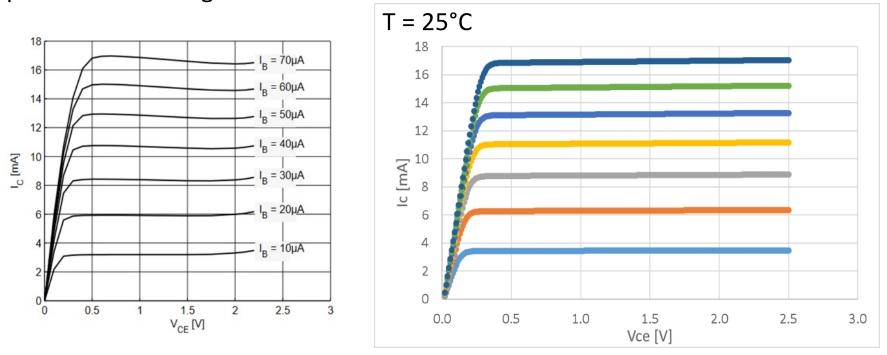
Summary

- Response of PiN and LGAD unirradiated devices simulated in SPICE
- Gain of the chain of amplifiers determined: 92.5 dB or 42,170
- Charge collection shows >15 fC charge collected for 1mm LGAD array device biased at >240 V (for unirradiated devices)
- 1mm LGAD array devices show jitter of <20 ps for bias >160 V
- Future improvements of laser optics setup should allow to refine jitter measurements remove contributions from trigger and laser jitter

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SPICE – DC Simulation of the SiGe NPN

- SiGe NPN BFR840L3RHESD (Infineon)
- Compare SPICE predictions with typical DC curves reported in the design sheet



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Martin Gazi, 39th RD50 Workshop

Q1

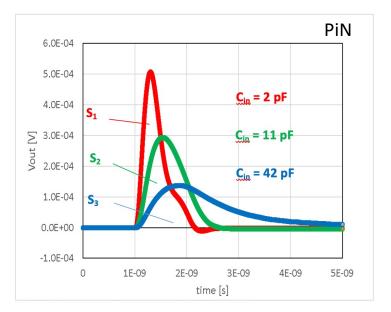
0

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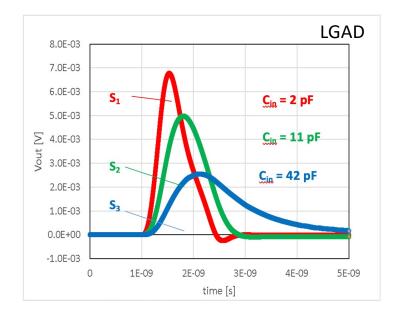
DET

BER840L3RHESE

SPICE – Transient current simulation

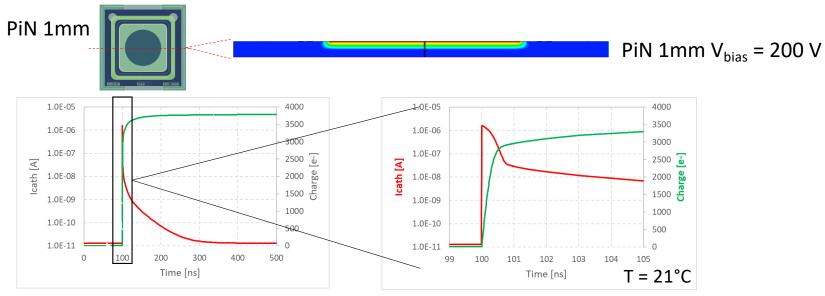


1st stage only



1 mm ≈ 2 pF 2 mm ≈ 11 pF

TCAD simulation for PiN(MIP)

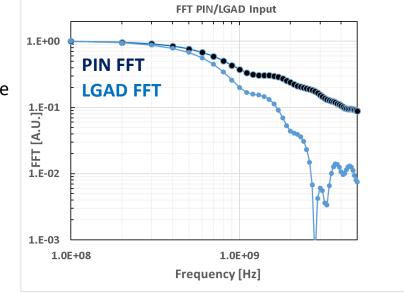


MIP transient current and collected charge for PiN diode at V_{bias} = 200 V

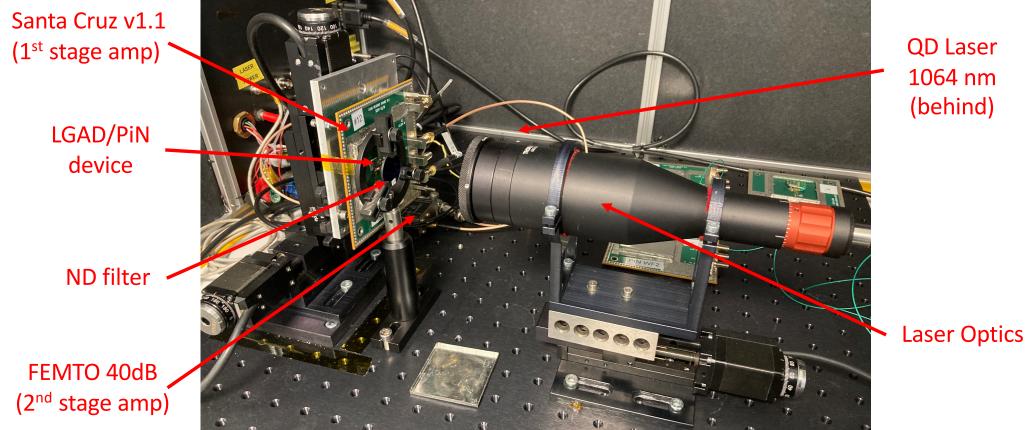
- MIP : MPV [300 um] ~ 72 e/h pair/um
- Central hit
- Time resolution $[t_0, t_0+1ns]$: 100 fs
- Implement the current waveform $[t_0, t_0 + 5 \text{ ns}]$ into SPICE simulation of RF amplifier
- TCAD estimated collected charge at 5 ns = 3303 e- (eqv. 0.53 [fC])

Normalized PiN and LGAD (MIP) FFT of current signal

 Comparison the FFT of the PiN and LGAD signals, normalized to their maximum magnitude



Charge collection and jitter - laser setup

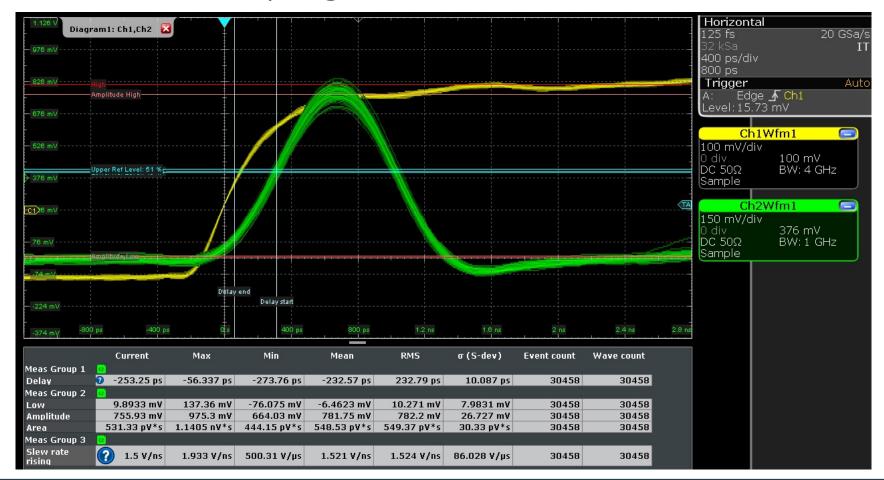


QD Laser 1064 nm (behind)

22

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1mm LGAD array signal – 240 V bias



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